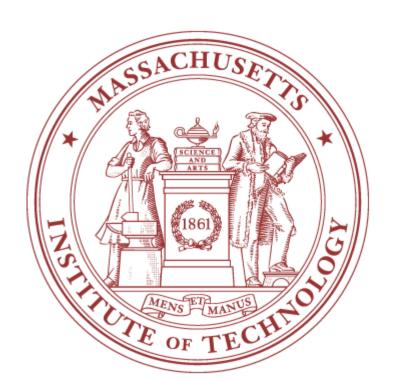


Laser Speckle Photography for Surface Tampering Detection



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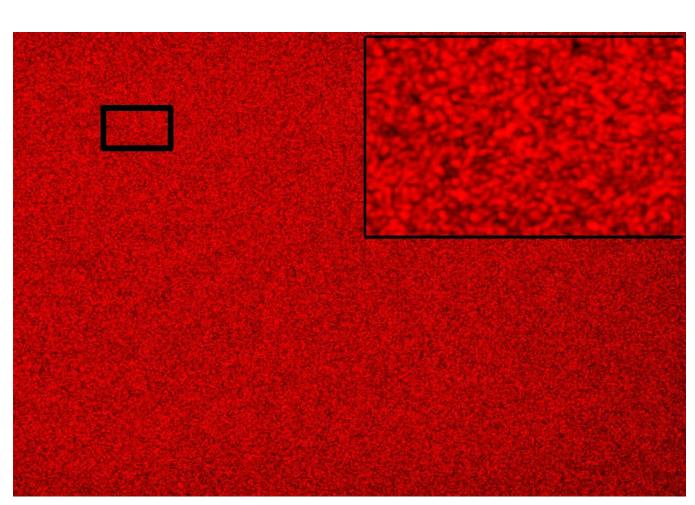
Abstract

It is often desirable to detect whether a surface has been touched, even when the changes made to that surface are too subtle to see in a pair of before and after images. To address this challenge, we introduce a new imaging technique that combines computational photography and laser speckle imaging.

Laser Speckle Photography

When shine a coherent light (laser) on a surface, a camera will capture a granular pattern, which is called speckle.

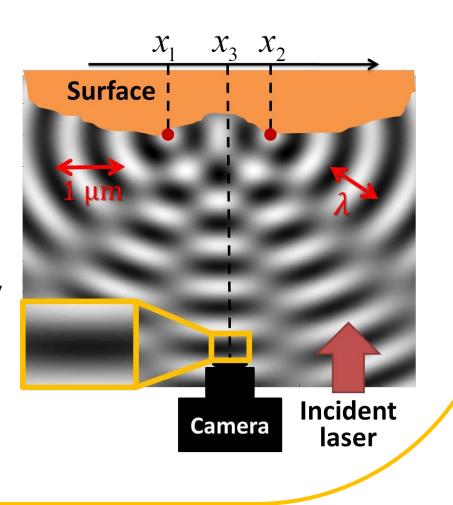




System setup

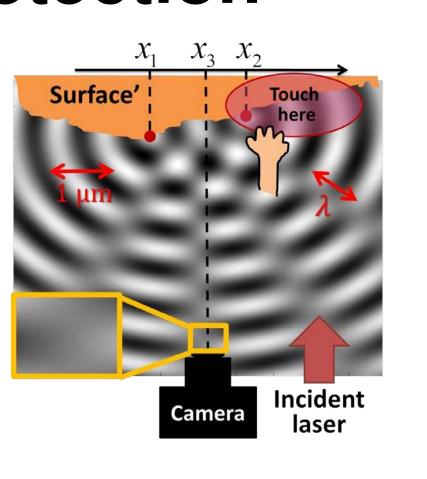
Speckle image

The speckle is caused by the interference of the laser light reflected from the surface. The speckle pattern is determined by the surface micro-geometry



Surface Tampering Detection

When the surface is tampered (eg. touched), the surface micro-geometry is changed, and so the speckle image is changed, even the changes are very small.



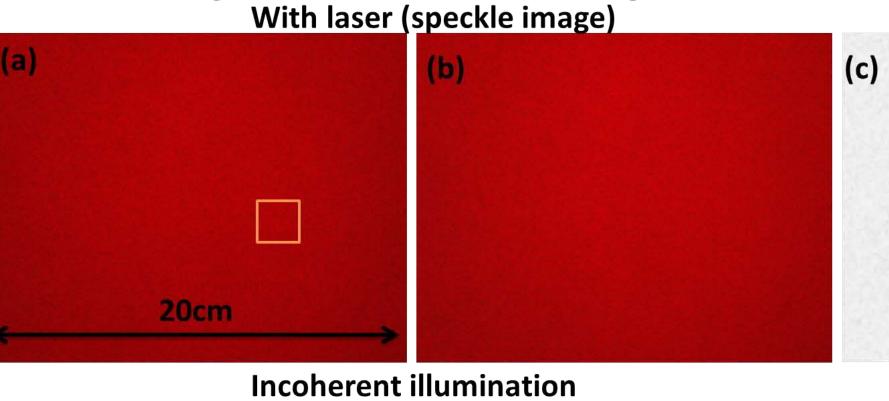
We take before and after speckle images of the surface to detect subtle change. Someone touched the surface between

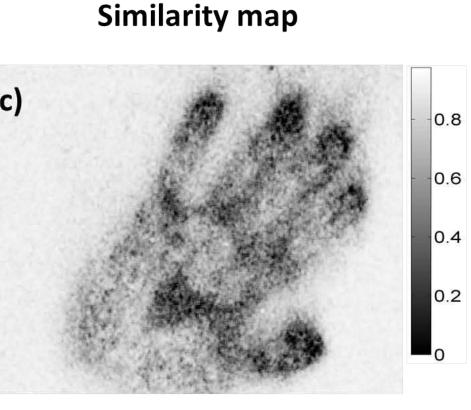
After touching the surface

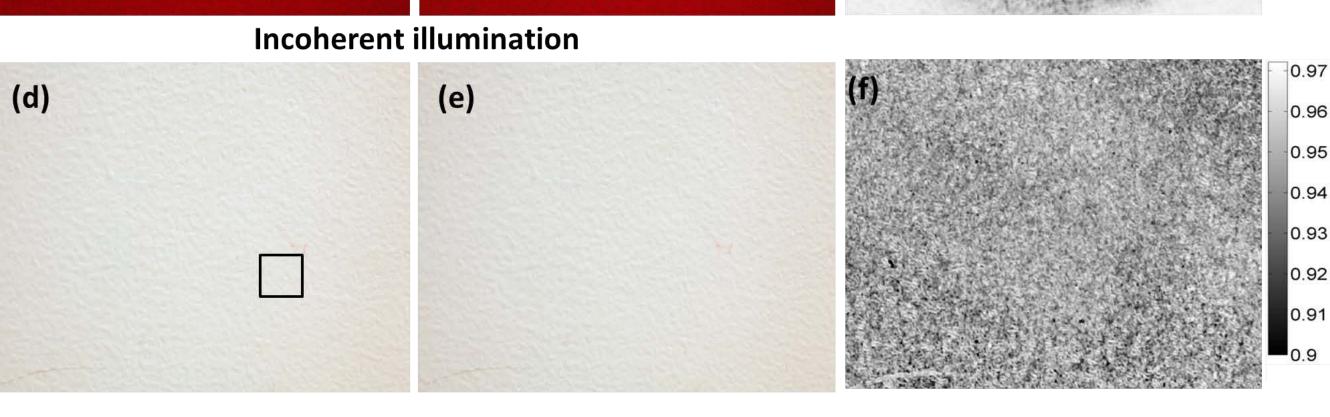
the two speckles.

Before touching the surface









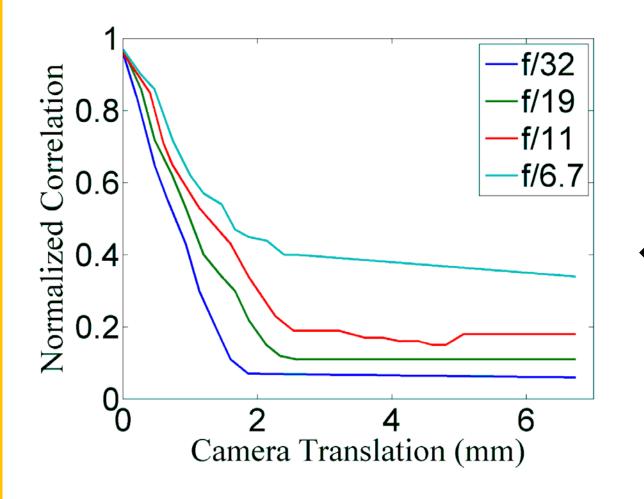
We visualize the tampered region by correlating the two speckle images

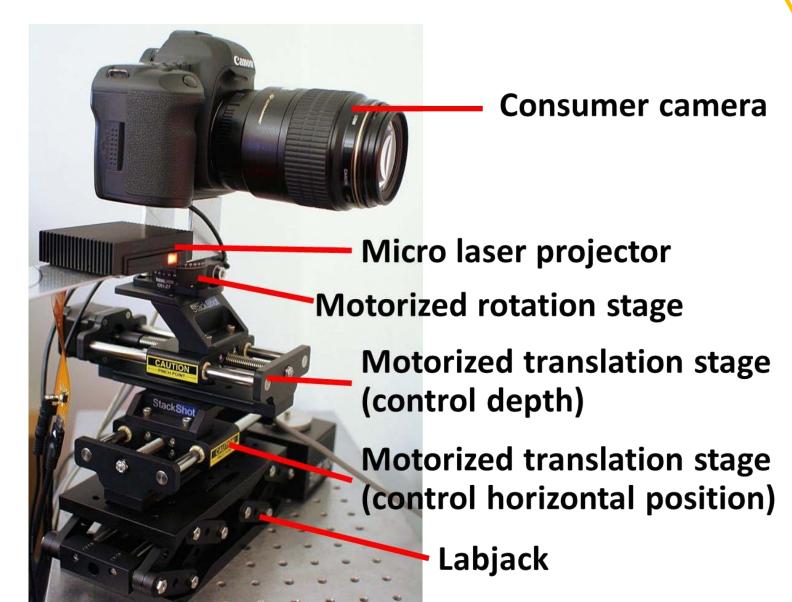
 $S(i,j) = NCC(W(i,j)I_{\text{tar}}, W(i,j)I_{\text{ref,w}})$



Rephotography

Our system is portable, out-of-lab setting, and can be removed during the two speckle images.





Speckle is very sensitive to camera viewpoint, so the alignment need to be very precise (about 1 mm)

Our solution takes two stages,

Feature-based localization by PTAM

- Accuracy about 2-3mm
- Not enough meet the requirement

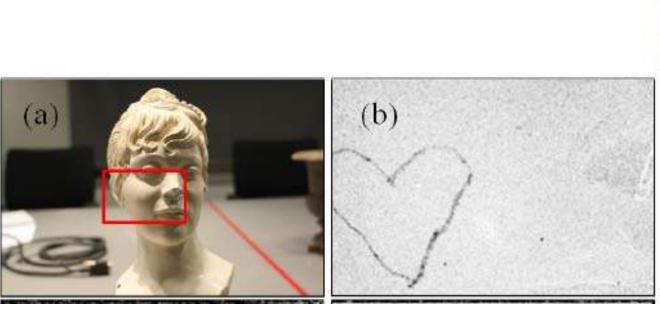
Speckle-based finer alignment

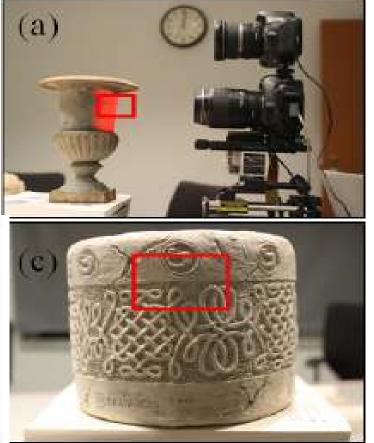
- Utilize the speckle sensitivity to viewpoint

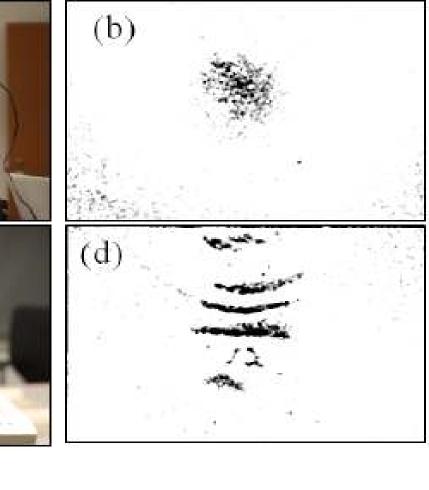
Works on Various Kinds of Materials



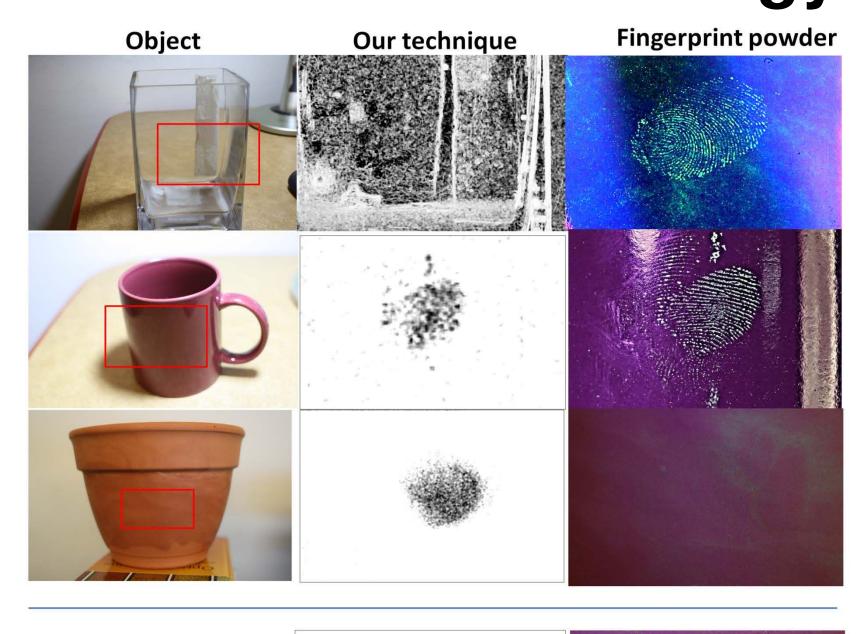








v.s. Forensic Technology



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